HS-VSP

- HS-VSP 铜箔低棱线特性具极佳的绝缘效果与具优越的蚀刻性之符合新一代环保要求之电解铜箔。

  HS-VSP foil with very low profile to have excellent insulation result and good etchability, and comply with environment regulation.
- 较低的粗糙度特性具優越的蝕刻性.

  Extra low profile to have excellent etchability.
- 銅箔穩定的量產能力, 可充分供應客戶需求.

  Our plant has stable capacity for HS-VSP to fulfill customer requirements.

用途/Application

・高速讯号传输板
/HSD (High speed digital)
・基地台/伺服器
/Base station / Server

结构 /Composition

生产地点 /Production Site

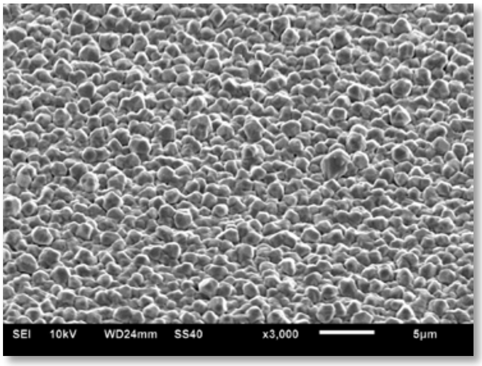
・台湾 / Taiwan

特性代表值/Representative data

	μm	Rz (μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)
HS-VSP	18	1.8	350	8	0.9
	35	1.8	350	16	1.1
	70	1.8	350	19	1.3

※上述表列为代表性数据非保证值。
This is representative data, not guarantee.

处理面/Laminate side



阻剂面/ Resist side